



# Nanolithography

The art of fabricating  
nanoelectronic and  
nanophotonic devices  
and systems

Edited by Martin Feldman

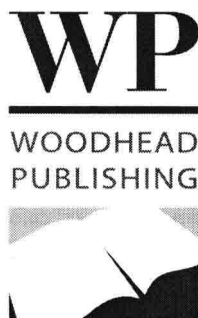
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## Contributor contact details

---

(\* = main contact)

### Editor

Martin Feldman  
Division of Electrical and  
Computer Engineering  
Patrick Taylor Hall  
Louisiana State University  
Baton Rouge  
LA 70803, USA  
E-mail: mfeldm1@lsu.edu

### Chapter 1

Bruce W. Smith  
Microsystems Engineering  
College of Engineering  
Rochester Institute of Technology  
168 Lomb Memorial Drive  
Rochester  
NY 14623, USA  
E-mail: bwsemc@rit.edu

### Chapter 2

Bryan J. Rice  
Intel Corporation assignee to  
SEMATECH  
257 Fuller Rd, Suite 2200  
Albany  
NY 12203, USA  
E-mail: bryan.rice@sematech.org

### Chapter 3

Timothy R. Groves  
College of Nanoscale Science and  
Engineering  
University at Albany, State  
University of New York  
257 Fuller Road  
Albany  
NY 12203, USA  
E-mail: tgroves@albany.edu

### Chapter 4

Mark Utlaut  
Department of Physics  
University of Portland  
MSC121  
5000 N. Willamette Blvd.  
Portland  
Oregon 97203, USA  
E-mail: utlaut@up.edu

### Chapter 5

Emily Gallagher\* and  
Michael Hibbs  
IBM Microelectronics Inc.  
1000 River Street  
Essex Junction  
VT 05452, USA  
E-mail: fisch@us.ibm.com and  
mhibbs@us.ibm.com

## Chapter 6

Michael Walsh and  
Feng Zhang  
LumArray, Inc.  
15 Ward Street  
Somerville  
MA 02143, USA

Rajesh Menon  
University of Utah  
Salt Lake City  
UT  
USA

Henry I. Smith\*  
LumArray, Inc.  
15 Ward Street  
Somerville  
MA 02143, USA  
and

Massachusetts Institute of  
Technology  
Cambridge  
MA 02139, USA  
E-mail: hismith@mit.edu

## Chapter 7

Anthony Novembre\*  
Princeton Institute for the Science  
and Technology of Materials  
Princeton University  
70 Prospect Ave.  
Princeton  
NJ 08540, USA

E-mail: novembre@Princeton.EDU

Sen Liu  
IBM Corporation  
2070 Route 52  
Hopewell Junction  
NY 12533, USA

E-mail: liuse@us.ibm.com

## Chapter 8

Shinji Matsui\*  
Laboratory of Advanced Science  
and Technology  
University of Hyogo  
3-1-2 Koto, Kamigori  
Ako  
Hyogo 678-1205, Japan  
E-mail: matsui@lasti.u-hyogo.ac.jp

Mikihito Takenaka  
Department of Polymer Chemistry,  
Graduate School of Engineering  
Kyoto University  
Kyotodaigaku-katsura  
Nishikyo-ku  
Kyoto 615-8510, Japan  
E-mail: takenaka@alloy.polym.  
kyoto-u.ac.jp

Hiroshi Yoshida  
Department of Organic Materials  
Research  
Hitachi Research Laboratory,  
Hitachi, Ltd.  
7-1-1 Omika  
Hitachi-city  
Ibaraki, 319-1292, Japan  
E-mail: hiroshi.yoshida.jz@hitachi.  
com

## Chapter 9

Doug Resnick  
Molecular Imprints Inc.  
1807 West Braker Lane  
Austin, TX USA 78758 USA  
E-mail: DResnick@  
molecularimprints.com

**Chapter 10**

Xing Cheng  
 Department of Electrical and  
 Computer Engineering  
 Texas A&M University  
 College Station  
 Texas 77843, USA  
 E-mail: chengx@ece.tamu.edu

**Chapter 11**

Pouya Dastmalchi,  
 Ali Haddadpour and  
 Georgios Veronis\*  
 School of Electrical Engineering &  
 Computer Science and Center for  
 Computation & Technology  
 Louisiana State University  
 3101 Patrick F. Taylor Hall Baton  
 Rouge Louisiana 70803,  
 USA  
 E-mail: gveronis@lsu.edu,  
 gveronis@gmail.com

**Chapter 12**

Theda Daniels-Race  
 Division of Electrical and  
 Computer Engineering  
 School of Electrical Engineering  
 and Computer Science  
 Louisiana State University  
 3197 Patrick F. Taylor Hall  
 Baton Rouge  
 LA 70803, USA  
 E-mail: tdrace@lsu.edu

**Chapter 13**

Li Jiang and  
 Naga S. Korivi  
 Electrical Engineering Department

Tuskegee University  
 Tuskegee,  
 Alabama, 36088, USA  
 E-mail: ljiang@mytu.tuskegee.edu

**Chapter 14**

Artak Isoyan and  
 Lawrence S. Melvin\* III  
 Synopsys Inc. 2025 NW Cornelius  
 Pass Road  
 Hillsboro  
 OR 97124, USA  
 E-mail: Isoyan@synopsys.com and  
 lmelvin@synopsys.com

**Chapter 15**

Euclid E. Moon  
 Massachusetts Institute of  
 Technology  
 Cambridge  
 MA 02139, USA  
 E-mail: euclid@nano.mit.edu

**Chapter 16**

Vassilios Constantoudis\* and  
 Evangelos Gogolides  
 Institute of Microelectronics  
 NCSR 'Demokritos'  
 Patr. Grigoriou and Neapoleos str.  
 Aghia Paraskevi 15310, Greece  
 E-mails: vconst@imel.demokritos.gr  
 evgog@imel.demokritos.gr

George P. Patsis  
 Department of Electronics  
 Technological Educational  
 Institution of Athens  
 Aegaleo 12210, Greece  
 E-mail: patsisg@teiath.gr



## Chapter 17

Filiz Yesilkoy and

Chad Ropp

Department of Electrical and

Computer Engineering

University of Maryland

College Park

MD 20742, USA

Zach Cummins and Roland Probst

Fischell Department of

Bioengineering

University of Maryland

College Park

MD 20742, USA

Edo Waks

Department of Electrical and

Computer Engineering

and

Institute for Research in

Electronics and Applied Physics

(IREAP)

University of Maryland

College Park

MD 20742, USA

Benjamin Shapiro

Fischell Department of

Bioengineering

and

The Institute for Systems Research

(ISR)

University of Maryland

College Park

MD 20742, USA

Martin Peckerar\*

Department of Electrical and

Computer Engineering

University of Maryland

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No one ever thought that Moore's law would go on forever, that feature widths would continue to decrease by a factor of two every six years, or that the number of gates on a chip would double every six years or so. But these rates have never slowed down; if anything, they have become slightly faster. And now, with features *in production* just a few dozen atoms wide, the end is almost in sight. How will we deal with features ten atoms wide? What if they're not always ten, but sometimes nine and sometimes eleven? Will we call the two in the middle the thumbs, and the two at the edges the pinkies? Suppose gates shrink to just a few atoms. What will the wires connecting them look like?

The paths we have taken to get this far are fascinating, often using effects that everyone knew about, but were too constrained by long-standing inhibitions to consider practical. For example, immersion microscopy, in which a liquid between the objective and the work-piece is used to improve resolution, was probably older than anyone working in lithography. But for many years the worst crime a lab technician could commit was to allow anything to touch the surface of a resist-coated wafer. Yet now, exposing wafers under water is the mainstream method for fine line patterning.

As another example, contact printing was, and still is, a method for obtaining medium levels of resolution. Combined with the shorter wavelengths of X-rays, it promised resolutions below 100 nm. But the inhibition against touching mask to wafer in a production environment was so strong that even a 10 micron gap between the mask and wafer was considered dangerously small. This was one of the factors that ultimately led to the abandonment of X-ray lithography. Yet now, imprinting, in which the mask is literally pushed into the resist, is a major contender for the next generation of lithography.

As a final example, it has been long recognized that isolated features can be made narrower than densely packed ones. The trick is to control the developing, so as not to make the feature width zero, i.e., not to lose the feature completely. In addition, the use of double exposures with stencil masks was well known. But the tighter control and the longer exposure time did not seem suitable for a production environment. Nevertheless, the use of a first exposure for every other feature, and a second exposure for the remaining features, is also a major contender for the next generation of lithography.

This book is intended as a guide to the novice reading technical journals or facing the complexities of a conference dealing with lithography or nano-manufacturing. The novice may be a graduate student to whom everything is new, or he/she may be an experienced worker in a peripheral field. The authors, all experts in their fields, were instructed to give enough background information to enable novices to understand, and appreciate, new papers in those fields. My thanks to them for their patience in accepting this challenge.

The future belongs to the novice, armed with the knowledge of the past, but unhampered by its inhibitions. How will Moore's law end? I look forward to finding out.

*M. Feldman*  
*August, 2013*



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